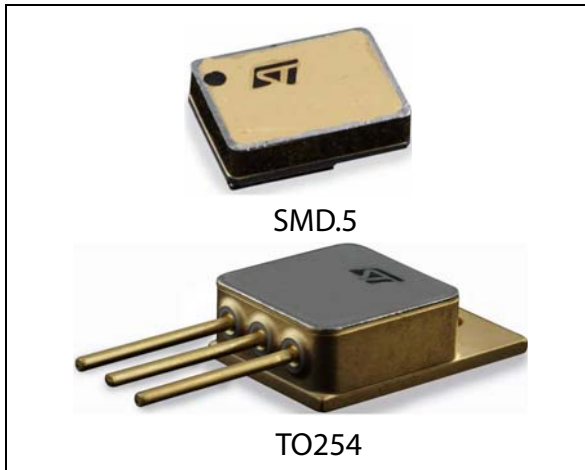


## Aerospace 1 x 20 and 2 x 20 A - 100 V Schottky rectifier

Datasheet - production data



### Features

- Forward current: 1 x 20 and 2 x 20 A
- Repetitive peak voltage: 100 V
- Low forward voltage drop: 0.8 V
- Maximum junction temperature: 175 °C
- Negligible switching losses
- Low capacitance
- High reverse avalanche surge capability
- Hermetic packages
- ESCC qualified

### Description

This power Schottky rectifier is designed and packaged to comply with the ESCC5000 specification for aerospace products. Housed in hermetically sealed packages both surface mount and through hole, it is ideal for use in applications for aerospace and other harsh environments.

The STPS20100HR is intended for use in medium voltage application and particularly, in high frequency circuits where low switching losses and low noise are required.

**Table 1. Device summary**

Order code	ESCC detailed specification	Quality level	Package	EPPL	IF (AV)	VRRM	T <sub>j</sub> (max)	V <sub>F</sub> (max)
STPS20100S1	-	Engineering model	SMD.5	-	1 x 20	100	175	1
STPS20100C2FY1	-	Engineering model	TO-254	-	2 x 20			
STPS20100SG	5106/016/05	ESCC Flight	SMD.5	Yes	1 x 20			
STPS20100C2FYT	5106/016/11	ESCC Flight	TO-254	-	2 x 20			

# 1 Characteristics

**Table 2. Absolute maximum ratings**

Symbol	Characteristic	Value	Unit
$I_{FSM}$	Forward surge current (per diode) <sup>(1)</sup>	250	A
$V_{RRM}$	Repetitive peak reverse voltage <sup>(2)</sup>	100	V
$I_{RRM}$	Repetitive peak reverse current <sup>(3)</sup>	1	A
$I_O$	Average output rectified current (50% duty cycle): <sup>(4), (5)</sup> All variants (per diode) Variants 11(per device)	20 40	A
$I_{F(RMS)}$	Forward rms current (per diode)	30	A
$T_{OP}$	Operating temperature range <sup>(6)</sup> (case temperature)	-65 to +175	°C
$T_J$	Junction temperature	+175	°C
$T_{STG}$	Storage temperature range <sup>(6)</sup>	-65 to +175	°C
$T_{SOL}$	Soldering temperature: For TO-254 <sup>(7)</sup> For SMD.5 <sup>(8)</sup>	+260 +245	°C
dV/dt	Critical rate of rise of reverse voltage	10000	V/μs

1. Sinusoidal pulse of 10 ms duration
2. Pulsed, duration 5 ms, F = 50 Hz
3. Pulsed, duration 2 μs, F = 1 kHz
4. For  $T_{case} > +140$  °C, derate linearly to 0 A at +175 °C.
5. The “per Device” ratings apply only as follows:  
Variant 02: when both cathode terminals are tied together  
Variant 03: when both anode terminals are tied together.
6. For variants with hot solder dip lead finish all testing performed at  $T_{amb} > +125$  °C are carried out in a 100% inert atmosphere.
7. Duration 10 seconds maximum at a distance of not less than 1.5 mm from the device body and the same lead shall not be re-soldered until 3 minutes have elapsed.
8. Duration 5 seconds maximum and the same package shall not be re-soldered until 3 minutes have elapsed.

**Table 3. Thermal resistance**

Symbol	Characteristic	Value	Unit
$R_{th(j-c)}^{(1)}$	Thermal resistance, junction to case Variants 05 Variants 11 (per device) <sup>(2)</sup>	1.65 0.85	°C/W

1. Package mounted on infinite heatsink
2. The per device ratings apply for variant 11 when both anode terminals are tied together.

Table 4. Electrical measurements at ambient temperature (per diode),  $T_{amb} = 22 \pm 3 \text{ }^\circ\text{C}$ 

Symbol	Characteristic	MIL-STD-750 test method	Test conditions	Values		Units
				Min.	Max.	
$I_R$	Reverse current	4016	DC method, $V_R = 100 \text{ V}$	-	30	$\mu\text{A}$
$V_{F1}^{(1)}$	Forward voltage	4011	Pulse method, $I_F = 10 \text{ A}$	-	780	mV
$V_{F2}^{(1)}$			Pulse method, $I_F = 20 \text{ A}$	-	1	V
C	Capacitance	4001	$V_R = 10 \text{ V}$ , $F = 1 \text{ MHz}$	-	700	pF
$Z_{th(j-c)}$	Relative thermal impedance, junction to case	3101	$I_H = 15 \text{ to } 40 \text{ A}$ , $t_H = 50 \text{ ms}$ $I_M = 50 \text{ mA}$ , $t_{md} = 100 \text{ }\mu\text{s}$	Calculate $\Delta V_F$		$^\circ\text{C/W}$

1. Pulse width  $\leq 680\mu\text{s}$ , Duty Cycle  $\leq 2\%$

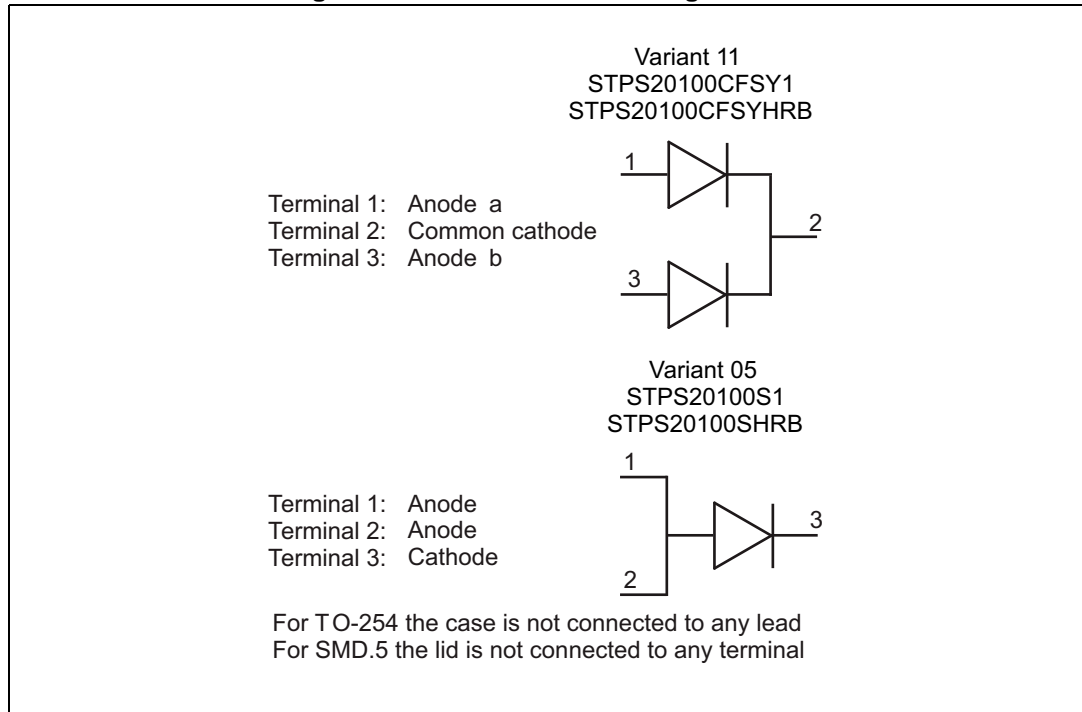
Table 5. Electrical measurements at high and low temperatures (per diode)

Symbol	Characteristic	MIL-STD-750 test method	Test conditions	Values		Units
				Min.	Max.	
$I_R$	Reverse current	4016	$T_{case} = +125 (+0, -5) \text{ }^\circ\text{C}$ DC method, $V_R = 100 \text{ V}$	-	20	mA
$V_{F2}^{(1)}$	Forward voltage	4011	$T_{case} = +125 (+0, -5) \text{ }^\circ\text{C}$ pulse method, $I_F = 20 \text{ A}$	-	900	mV
			$T_{case} = -55 (+5, -0) \text{ }^\circ\text{C}$ pulse method, $I_F = 20 \text{ A}$	-	1.1	V

1. Pulse width  $\leq 680\mu\text{s}$ , Duty Cycle  $\leq 2\%$

## 2 Configurations

Figure 1. Available device configurations

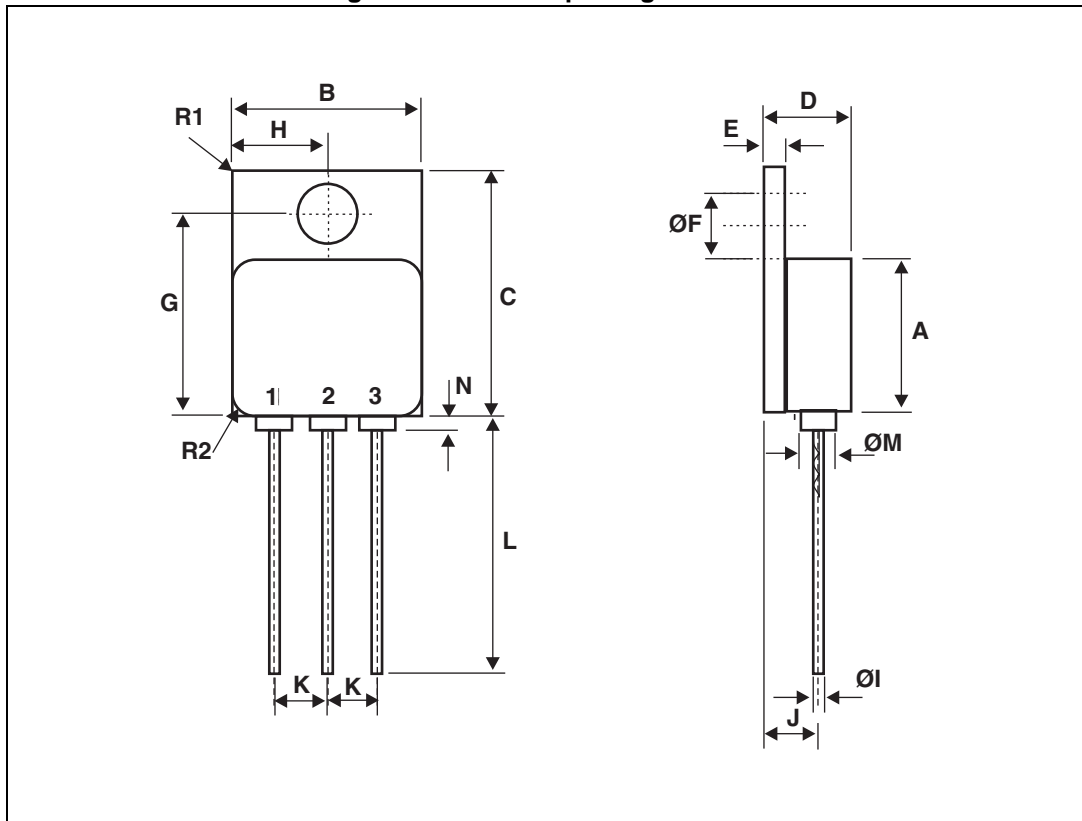


### 3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

#### 3.1 TO-254 package information

Figure 2. TO-254<sup>(a)</sup> package outline



a. The terminal identification is specified by the device configuration. See [Figure 1](#) for terminal connections

Table 6. TO-254 package mechanical data

Reference	Dimension in millimeters		Dimension in inches	
	Min.	Max.	Min.	Max.
A	13.59	13.84	0.535	0.545
B	13.59	13.84	0.535	0.545
C	20.07	20.32	0.790	0.800
D	6.3	6.7	0.248	0.264
E	1	3.9	0.039	0.154
ØF	3.5	3.9	0.138	0.154
G	16.89	17.4	0.665	0.685
H	6.86 BSC		0.270 BSC	
ØI <sup>(1)</sup>	0.89	1.14	0.035	0.045
J	3.81 BSC		0.150 BSC	
K	3.81 BSC		0.150 BSC	
L	12.95	14.5	0.510	0.571
ØM	3.05 Typ.		0.120 Typ.	
N	-	0.71	-	0.028
R1 <sup>(2)</sup>	-	1	-	0.039
R2 <sup>(3)</sup>	1.65 Typ.		0.065	

1. 3 locations
2. Radius of heatsink flange corner - 4 locations
3. Radius of body corner - 4 locations

### 3.2 SMD.5 package information

Figure 3. SMD.5 package outline

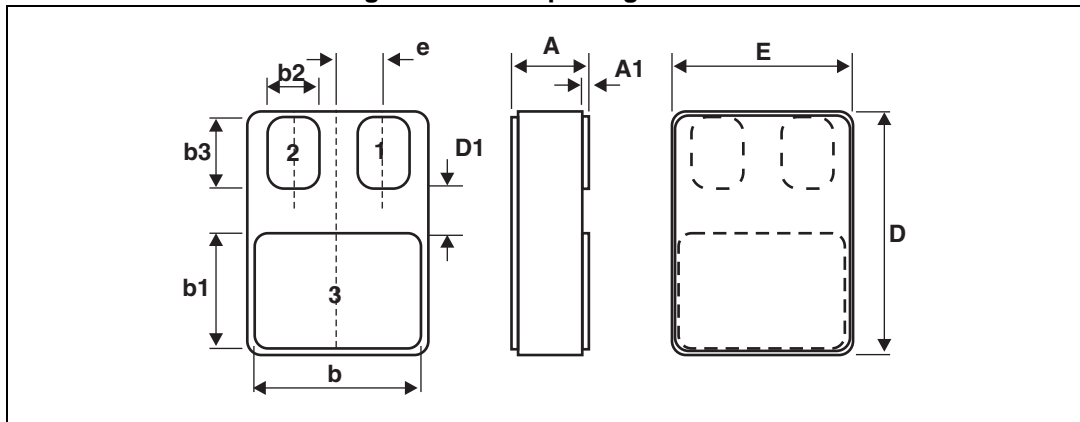


Table 7. SMD.5 package mechanical data

Reference	Dimension in millimeters		Dimension in inches	
	Min.	Max.	Min.	Max.
A	2.84	3.15	0.112	0.124
A1	0.25	0.51	0.010	0.20
b	7.13	7.39	0.281	0.291
b1	5.58	5.84	0.220	0.230
b2 <sup>(1)</sup>	2.28	2.54	0.090	0.100
b3 <sup>(1)</sup>	2.92	3.18	0.115	0.125
D	10.03	10.28	0.395	0.405
D1 <sup>(1)</sup>	0.76	-	0.030	-
E	7.39	7.64	0.291	0.301
e <sup>(1)</sup>	1.91 BSC		0.075	

1. 2 locations

## 4 Ordering information

**Table 8. Ordering information**

Order code	ESCC detailed specification	Package	Lead finish	Comment	Marking <sup>(1)</sup>	Mass	EPPL	Packing
STPS20100S1	-	SMD.5	Gold	Single die	STPS20100S1	2	-	Strip pack
STPS20100C2FY1	-	TO-254	Gold	Double die - common cathode	STPS20100C2FY1 + BeO	10	-	
STPS20100SG	5106/016/05	SMD.5	Gold	Single die	510601605	2	Yes	
STPS20100C2FYT	5106/016/11	TO-254	Solder Dip	Double die - common cathode	510601611 +BeO	10	-	

1. Specific marking only. The full marking includes in addition: For the engineering models: ST logo, date code, country of origin (FR). For ESCC flight parts: ST logo, date code, country of origin (FR), ESA logo, serial number of the part within the assembly lot.

## 5 Revision history

**Table 9. Document revision history**

Date	Revision	Changes
25-Mar-2010	1	Initial release.
19-Mar-2014	2	Updated <a href="#">Table 1: Device summary</a> , <a href="#">Table 8: Ordering information</a> and <a href="#">Figure 1: Available device configurations</a> .
10-Sep-2015	3	Update <a href="#">Features</a> and <a href="#">Table 8</a> . Reformatted to current standards.



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